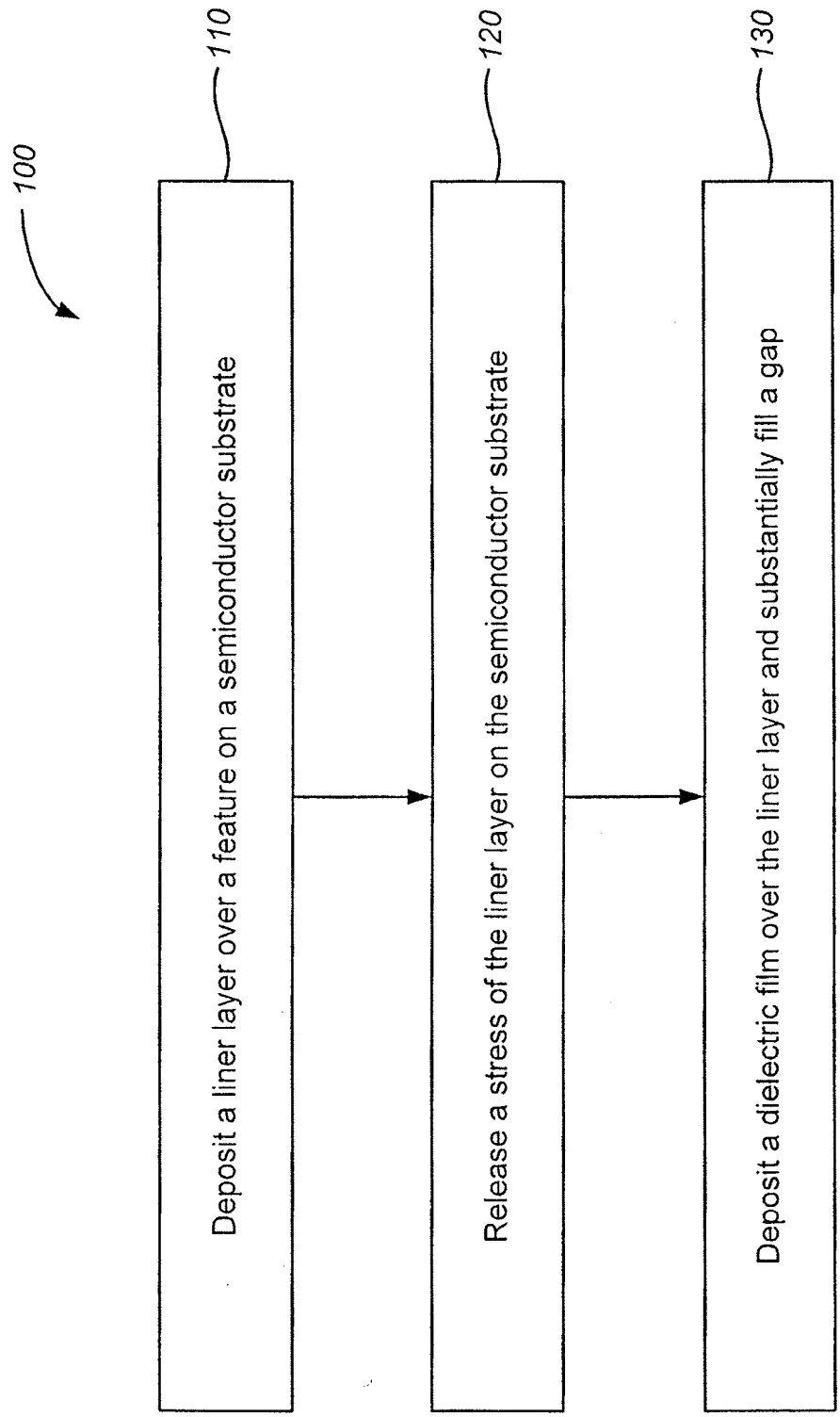

100
110
120
130
Deposit a liner layer over a feature on a semiconductor substrate
Release a stress of the liner layer on the semiconductor substrate
Deposit a dielectric film over the liner layer and substantially fill a gap

FIG. 1

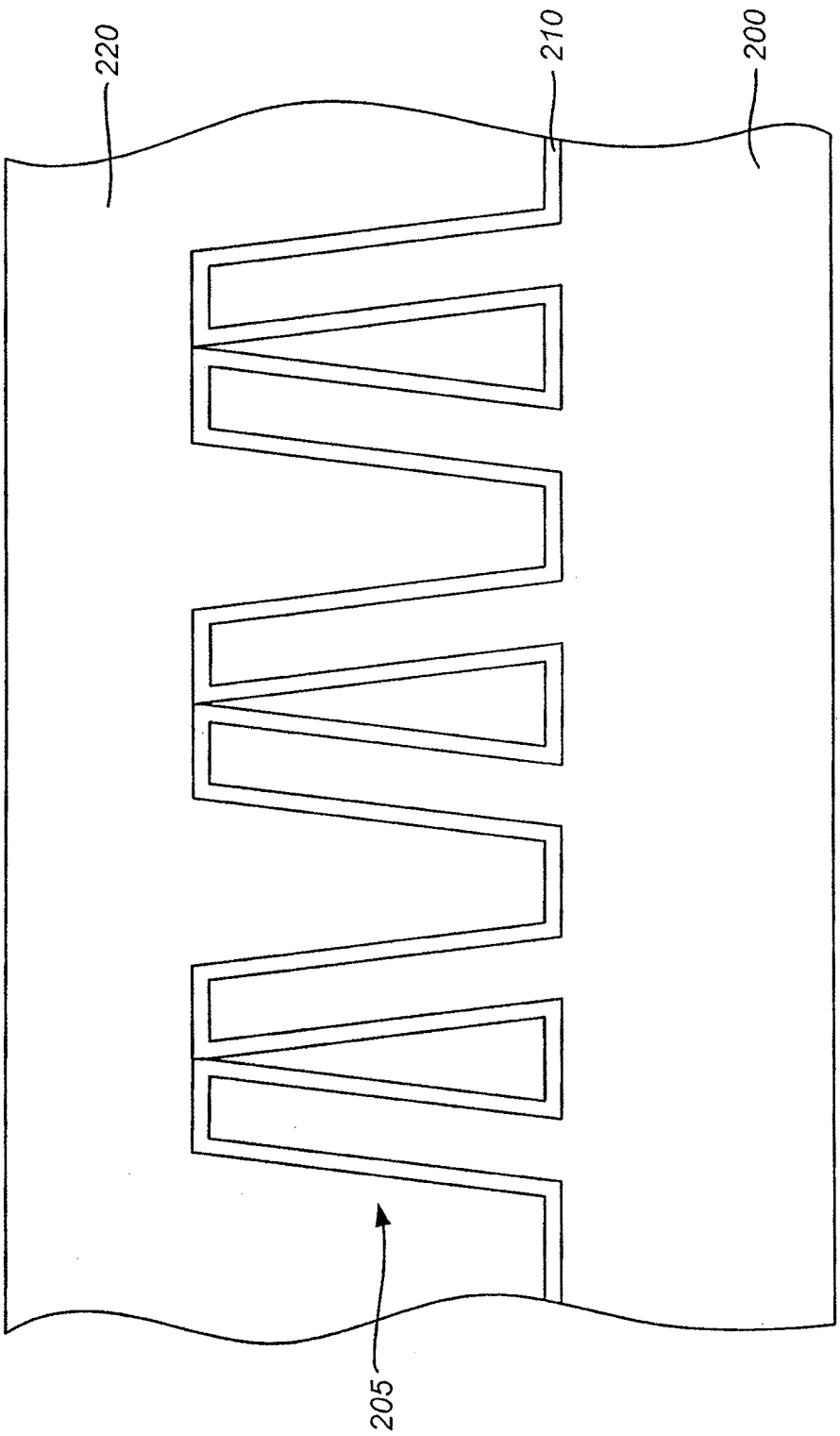


FIG. 2

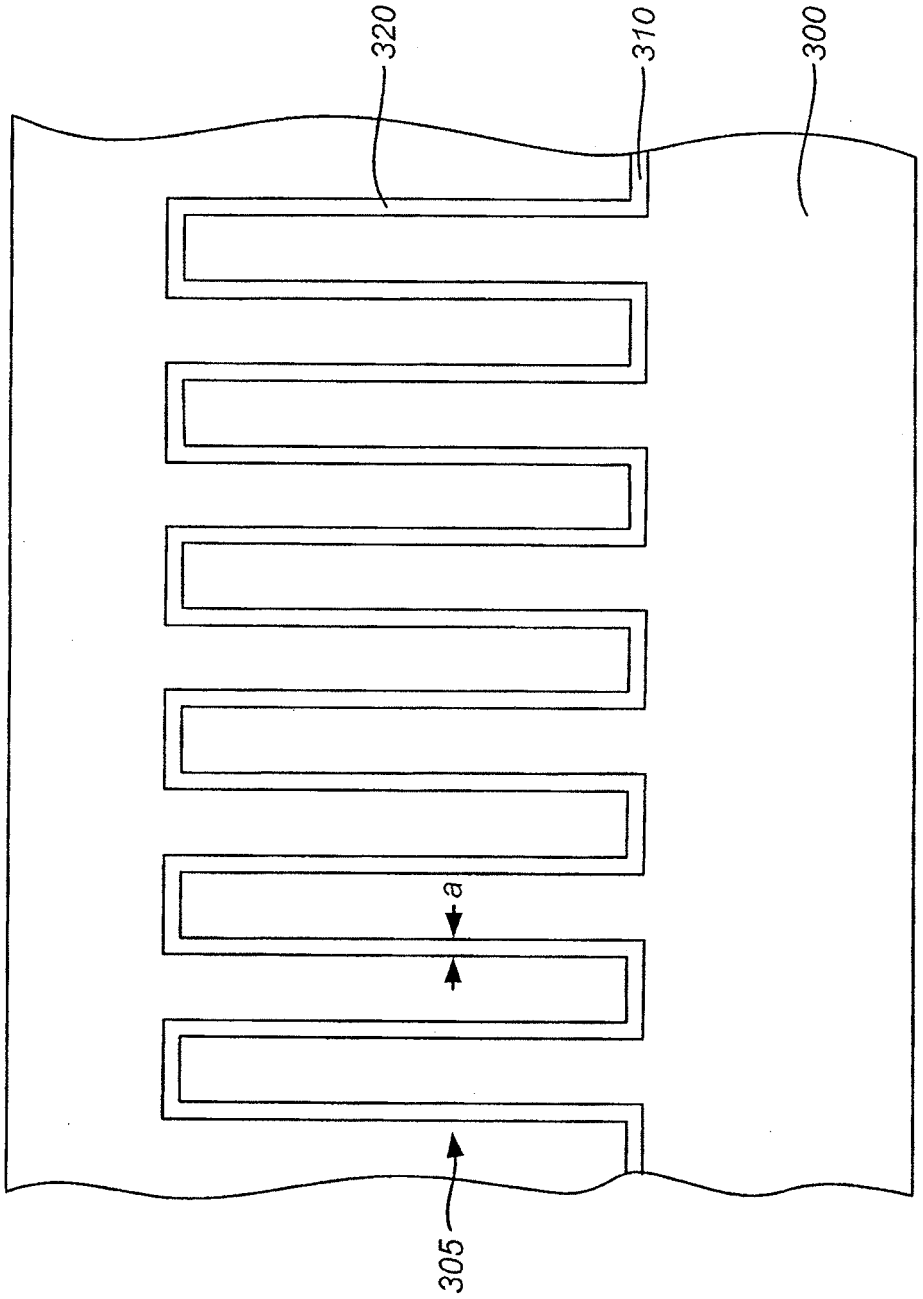


FIG. 3

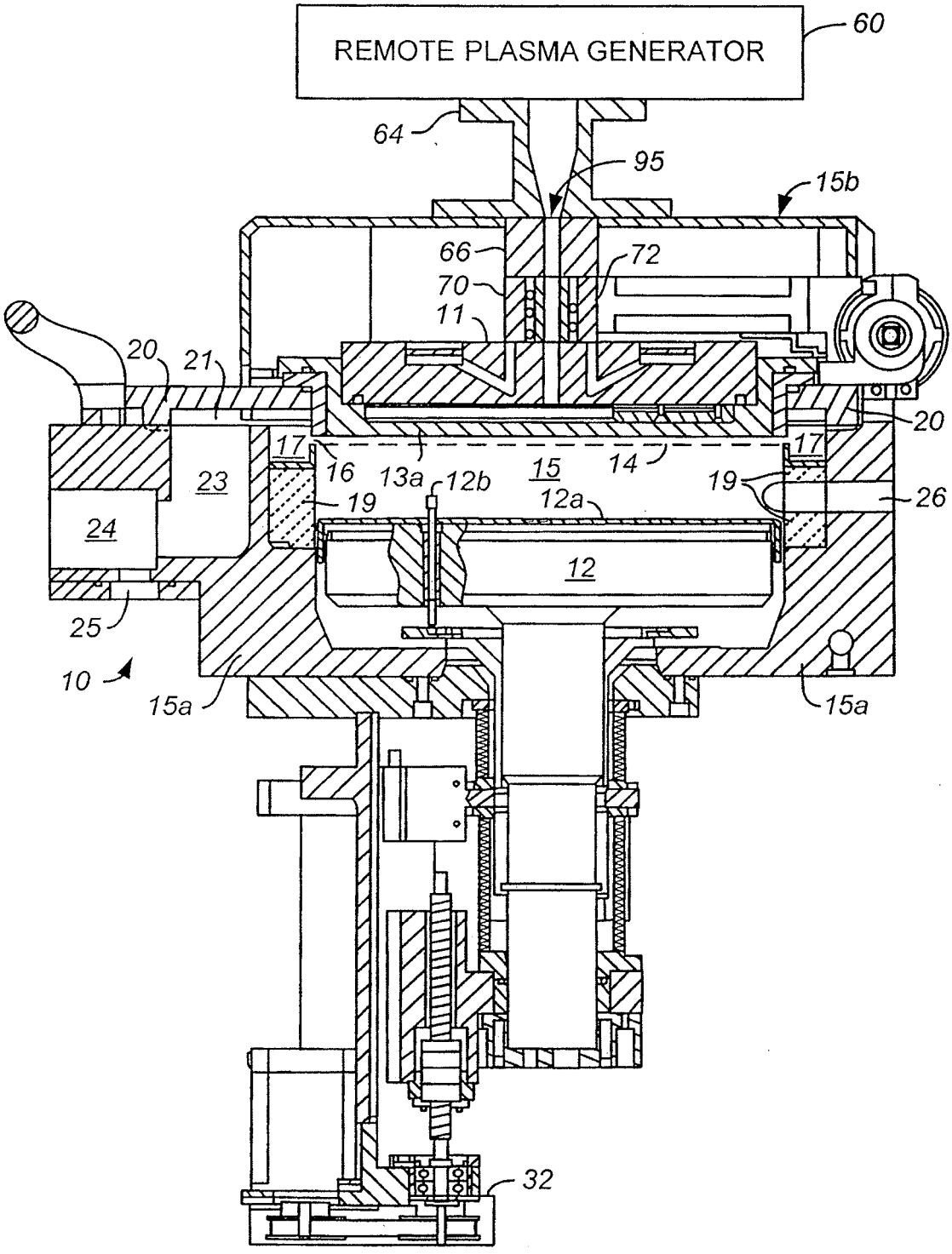

REMOTE PLASMA GENERATOR
60
64
95
15b
66
72
70
11
20
21
20
17
16
13a
12b
15
14
17
19
12a
19
26
23
24
12
25
10
15a
15a
32

FIG. 4A

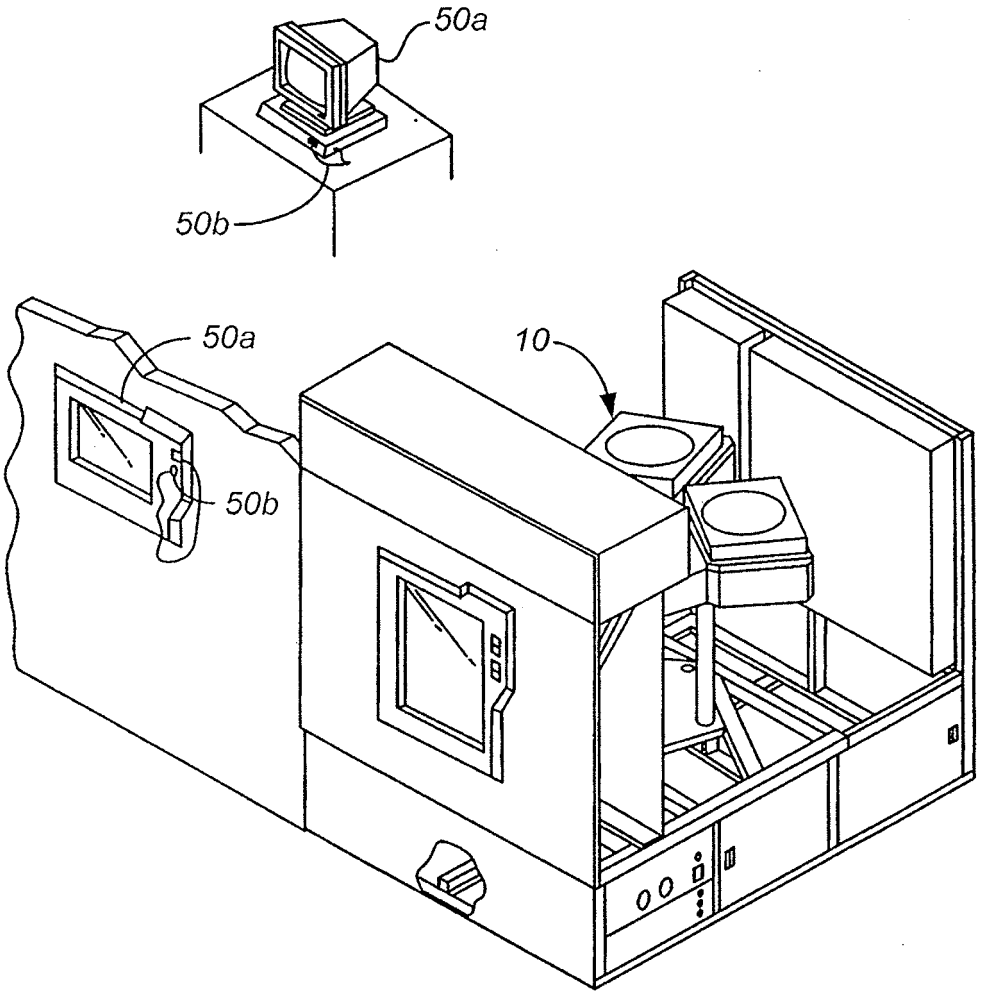


FIG. 4B